**Minutes – 280818**

**Present: HH, SW, AG, DS, SB, JT**

**Apologies: PS, TJ**

**Strip modules**

Liam starts 3rd Sep.

Glue 2nd electrical module. LB/SW. get power board today/tomorrow. Craig received from Timon this week. The one module without power board could only be powered to 300V.

Itk/strip decision about pcb. RAL person back from paternity is now back and not happy. New decision expected tomorrow. Craig overruling and being autocratic. We want one flavour without cutout. Impacts Sven’s work. Need to start buying tools.

AG forgot to tell sven they are using clinch nuts that he has to take account on jig.

On tooling: some comments from IW. Agree to have f2f on 12th or 13th sep at Liverpool to discuss. (IW, craig+liv).

**Strip Mechanics**

Stavve core: 1st step completed. Hamish completed measuring. Prep work completed. Small changes like Kapton tape too thin. Will be bespoke.

There is a written description on procedure with lots of caveats and asterisks. Hamish is documenting in twiki page. On target for next LAU meeting.

**Pixel modules**

JT: 8 4 RD53a chips paralene coated ready for irradiation and testbeam .

Should have 8 single chip cards. Should be back 2-3 weeks, ready for oct testbeam slot.

Should get another single chip card from Glasgow to test YARR readout. Last functional chip so needs to be sent to oxford. It is fully bump bonded. We have it for 2 weeks. Oxford need a play before testbeam.

Meanwhile Glasgow are trying to get more chips from states.

IT: boxes are made for bent hybrids. We need to make for Liverpool – make as we go. (1 hr each)

Modules: still waiting for oxford for greenlight. They need to thermal cycle. Glasgow not started production. They were waiting for oxford.

We start module production for ring0. -> paper for 4, stamp for 5th.

IT for this week: tomorrow we discuss adapter cards for ring0 .

2 designs of wafers: Cern pixel 8, cern pixel 9 => 2 designs of flexes.

Complete electronics for Tim today. From tomorrow just silicon design. Micron visit on 12th October. Investigate renting card. PD may also go.

Need long term plan:

YY has tested Yarr scripts from Timon.

Timon has sent only working chip. Sent to Jon. Should be here today/tomorrow.

YG will be at Lancaster for 2 weeks: YG has joint student from China. Experience with FPGA. Work with Jon Taylor.

**Pixel Mechanics**

Stalled whilst PS away.

TJ has emailed Danilo G. TJ to email outer barrel and inner pixel people, and cc Danilo.

Wednesday: milestones for pixel structures.

*Have quotes for CF – much more expensive that we originally though. We are now asking for cyanate ester*

*Do we really need the expensive one? We have experience through the face sheets.*

* *As PC to follow up.*

**AOB**

**HH-> get pizza night date.**

SW to sort travel documentation.

Gill Birch and Tricia is on holiday.

SW can now order through SBS.

HH needs to sort LAU